XPT IGBT

preliminary

V_{CES} 1200 V

I _{C25} 9 A

 $V_{CE(sat)}$ = 1.8 V

Single IGBT

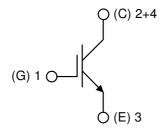
Part number

IXA4I1200UC

Marking on Product: X4TAU



Backside: collector



Features / Advantages:

- Easy paralleling due to the positive temperature coefficient of the on-state voltage
- Rugged XPT design (Xtreme light Punch Through)
 - short circuit rated for 10 µsec.
- very low gate charge
- low EMI
- square RBSOA @ 3x Ic
- Thin wafer technology combined with the XPT design results in a competitive low VCE(sat)

Applications:

- AC motor drives
- Solar inverter
- Medical equipment
- Uninterruptible power supply
- Air-conditioning systems
- Welding equipment
- Switched-mode and resonant-mode power supplies
- Inductive heating, cookers
- Pumps, Fans

Package: TO-252 (DPak)

- Industry standard outline
- RoHS compliant
- Epoxy meets UL 94V-0

Terms _Conditions of usage:

The data contained in this product data sheet is exclusively intended for technically trained staff. The user will have to evaluate the suitability of the product for the intended application and the completeness of the product data with respect to his application. The specifications of our components may not be considered as an assurance of component characteristics. The information in the valid application- and assembly notes must be considered. Should you require product information in excess of the data given in this product data sheet or which concerns the specific application of your product, please contact the sales office, which is responsible for you.

Due to technical requirements our product may contain dangerous substances. For information on the types in question please contact the sales office, which is responsible for you.

Should you intend to use the product in aviation, in health or live endangering or life support applications, please notify. For any such application we urgently recommend

- to perform joint risk and quality assessments; the conclusion of quality agreements;
- to establish joint measures of an ongoing product survey, and that we may make delivery dependent on the realization of any such measures.

IXYS reserves the right to change limits, conditions and dimensions.

Data according to IEC 60747 and per semiconductor unless otherwise specified

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IGBT					Ratings			
Symbol	Definition		Conditions		min.	typ.	max.	Unit
V _{CES}	collector emitter voltage			$T_{VJ} = 25^{\circ}C$			1200	V
V _{GES}	max. DC gate voltage						±20	٧
V_{GEM}	max. transient gate emitter voltage						±30	V
I _{C25}	collector current			$T_C = 25^{\circ}C$			9	Α
I _{C100}				$T_C = 100 ^{\circ}C$			5	Α
P _{tot}	total power dissipation			$T_{C} = 25^{\circ}C$			45	W
V _{CE(sat)}	collector emitter saturation voltage		$I_{C} = 3A; V_{GE} = 15 V$	$T_{VJ} = 25^{\circ}C$		1.8	2.1	V
				$T_{VJ} = 125 \circ C$		2.1		V
$V_{GE(th)}$	gate emitter threshold voltage		I_{C} = 0.1 mA; V_{GE} = V_{CE}	$T_{VJ} = 25^{\circ}C$	5.4	5.9	6.5	V
I _{CES}	collector emitter leakage current		$V_{CE} = V_{CES}; V_{GE} = 0 V$	$T_{VJ} = 25^{\circ}C$			0.1	mA
				$T_{VJ} = 125 \circ C$		0.1		mΑ
I _{GES}	gate emitter leakage current		$V_{GE} = \pm 20 \text{ V}$				500	nA
$Q_{G(on)}$	total gate charge		$V_{CE} = 600 \text{ V}; V_{GE} = 15 \text{ V}; I_{C} =$	3 A		12		nC
t _{d(on)}	turn-on delay time)				70		ns
t _r	current rise time		inductive load	T 125°C		40		ns
$\mathbf{t}_{d(off)}$	turn-off delay time	l		T _{VJ} = 125°C		250		ns
t _f	current fall time		$V_{CE} = 600 V; I_{C} = 3 A$ $V_{GE} = \pm 15 V; R_{G} = 330 \Omega$			100		ns
E _{on}	turn-on energy per pulse		$V_{GE} = \pm 15 \text{ V}, \Pi_{G} = 330 \Omega$			0.4		mJ
E_{off}	turn-off energy per pulse	ノ				0.3		mJ
RBSOA	reverse bias safe operating area	1	$V_{GE} = \pm 15 \text{ V}; R_G = 330 \Omega$	T _{VJ} = 125°C				1
I _{CM}		\int	$V_{CEmax} = 1200 V$				9	Α
SCSOA	short circuit safe operating area	7	$V_{CEmax} = 1200 \text{ V}$					
tsc	short circuit duration	}	$V_{CE} = 900 \text{ V}; V_{GE} = \pm 15 \text{ V}$	$T_{VJ} = 125$ °C			10	μs
I _{sc}	short circuit current	J	$R_G=330 \Omega$; non-repetitive			12		Α
R _{thJC}	thermal resistance junction to case						2.7	K/W
R _{thCH}	thermal resistance case to heatsink					0.50		K/W

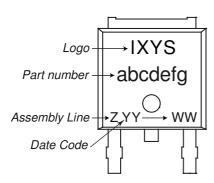




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Package TO-252 (DPak)			Ratiu			
Symbol	Definition	Conditions	min.	typ.	max.	Unit
I _{RMS}	RMS current	per terminal			20	Α
T _{vJ}	virtual junction temperature		-40		150	°C
T _{op}	operation temperature		-40		125	°C
T _{stg}	storage temperature		-40		150	°C
Weight				0.3		g
F _c	mounting force with clip		20		60	N

Product Marking



Part description

I = IGBT

X = XPT IGBT

A = Gen 1 / std

4 = Current Rating [A]

I = Single IGBT

1200 = Reverse Voltage [V]

UC = TO-252AA (DPak)

Ordering	Ordering Number	warking on Froduct	Delivery Mode	Quantity	Code No.
Standard	IXA4I1200UC	X4TAU	Tape & Reel	2500	

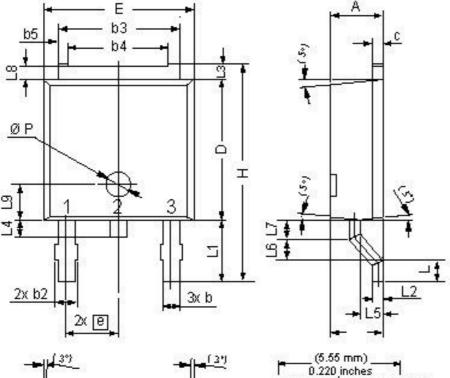
Equiv	alent Circuits for Simulation	* on die level	$T_{VJ} = 150 ^{\circ}\text{C}$
$I \rightarrow V_0$)- <u>R₀</u> -	IGBT	
V _{0 max}	threshold voltage	1.1	V
R_{0max}	slope resistance *	460	$m\Omega$



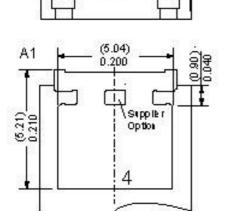
LIXYS

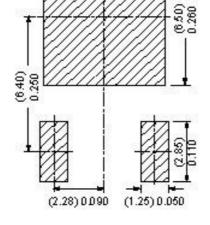
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Dim.	Millimeters		Inches		
Dini.	min	max	min	max	
Α	2.20	2.40	0.087	0.094	
A1	2.10	2.50	0.083	0.098	
b	0.66	0.86	0.026	0.034	
b2	100	0.96	, Q	0.038	
b3	5.04	5.64	0.198	0.222	
b4	4.34	BSC	0.171	BSC	
b5	0.50 BSC		0.020 BSC		
С	0.40	0.86	0.016	0.034	
D	5.90	6.30	0.232	0.248	
Е	6.40	6.80	0.252	0.268	
е	2.10	2.50	0.083	0.098	
Н	9.20	10.10	0.362	0.398	
L	0.55	1.28	0.022	0.050	
L1	2.50	2.90	0.098	0.114	
L2	0.40	0.60	0.016	0.024	
L3	0.50	0.90	0.020	0.035	
L4	0.60	1.00	0.024	0.039	
L5	0.82	1.22	0.032	0.048	
L6	0.79	0.99	0.031	0.039	
L7	0.81	1.01	0.032	0.040	
L8	0.40	0.80	0.016	0.031	
L9	1.50 BSC		0.059	BSC	
ØP	1.00	BSC	0.039	BSC	





Recommended min. foot print

